

TexEDA Design Inc to Showcase New LayTOOLS® Enhancements at DAC 2011 Conference

*New Multi-Project Wafer Optimization Tool,
Automated Bus Support, Headline TexEDA Participation*

SAN DIEGO, June 06, 2011 – TexEDA Design Inc will demonstrate this week at the annual Design Automation Conference (DAC) in San Diego its sustained commitment to providing the latest in design flows and EDA tool advancements for analog and mixed signal IC design, showcasing its service-oriented EDA tool suite, **LayTOOLS**. LayTOOLS has provided a fast, powerful, flexible and cost effective design environment to corporate users as well as individual IC professionals for over 20 years.

During DAC 2011, the leading technical conference and trade show for users and practitioners of electronic design automation worldwide, TexEDA will highlight the newest addition to the LayTOOLS software suite, **LayMPW**®, designed for multi-project wafer optimization, as one of several significant additions, enhancements and demonstrations at the event.

“LayMPW offers foundries and companies which may wish to submit multiple die for a single process run a quick and powerful environment to optimize MPW silicon area,” said John Campbell, President, TexEDA Design Inc. “Using the advanced algorithms we've developed at the heart of our LayMPW reticle assembly tool, die size restrictions can now be a thing of the past.”

Participating at the 48th DAC conference TexEDA also will demonstrate for IC Design professionals attending the show the new automated bus support capabilities of **LayED**®, a powerful all-angles graphics editor especially developed for the layout of complex integrated circuits, including analog, rf, digital, and mixed-signal designs.

Visitors to the **TexEDA booth #3119** during DAC 2011 also will be able to learn about new enhancements to the LayTOOLS professional grade IC Design Suite:

* PDKs	custom foundry interfaces
* RLM	software based license management
* LayFRAME	comprehensive project design manager
* LaySIM	mixed-signal simulator (<i>powered by SMASH</i> ®)
* LayED	enhanced bus support
* LayMPW	multi-project wafer optimization tool
* 32/64 bit support	PC, Linux, Solaris
* <i>matricus inc.</i>	professional design and layout services

More information about TexEDA activities in support of EDA can be obtained from TexEDA executives at **booth #3119** at DAC 2011, June 6-8, 2006 at the San Diego Convention Center.

About TexEDA Design Inc.

TexEDA Design Inc. is an established leader in electronic design automation (EDA) software, supplying the global IC design market with LayTOOLS software, a mixed-mode IC development suite with modules covering all the disciplines from simulation to physical verification under the umbrella of a design manager framework. LayTOOLS is recognized worldwide for the unparalleled value proposition it makes to the IC design marketplace. TexEDA Design is headquartered in Lewisville, Texas. www.LayTOOLS.com

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